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TFT Display Module

Part Number

E26RB-FS500-N

Overview:

- 2.6-inch TFT: 320x432 (46.76x65.85)
- 3/4 SPI+16/18-bit RGB
- 8/9/16/18-bit MCU
- 3-line/4-line Serial Interface
- White LED back-light
- Transflective/ Normally Black
- No Touch Panel
- 500 NITS
- Controller: ILI9488
- RoHS Compliant

Description

This is a color active matrix TFT (Thin Film Transistor) LCD (Liquid Crystal Display) that uses amorphous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 2.8" TFT-LCD contains 320x240 pixels, and can display up to 65K colors.

Features

Low Input Voltage: 3.3V (TYP)

Display Colors of TFT LCD: 65K/262K colors

TFT Interface: 8/9/16/18-bit MCU;

3/4-bit SPI+16/18-bit RGB

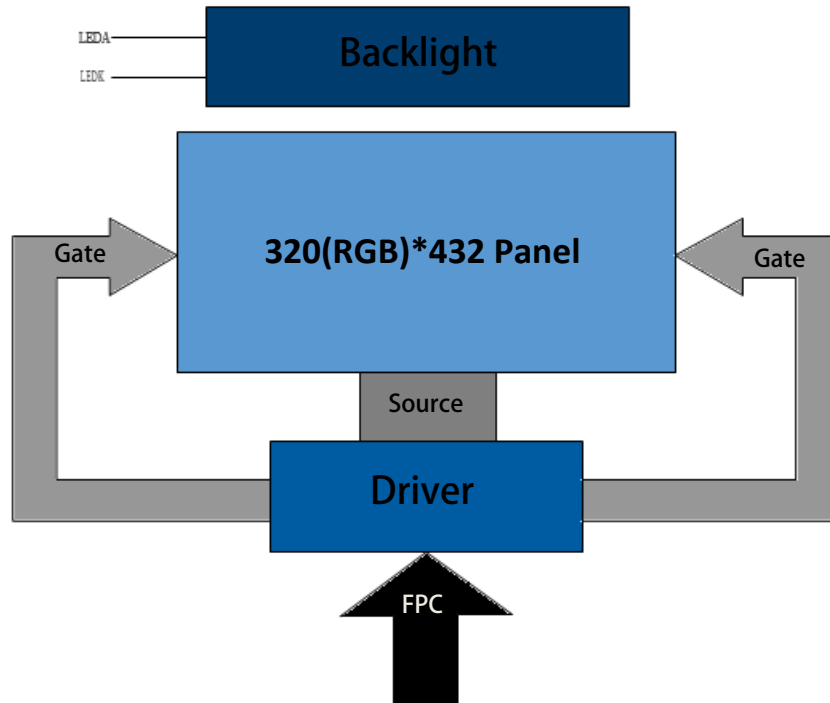
3-line/4-line Serial Interface

General Information Items	Specification	Unit	Note
	Main Panel		
Display area (AA)	3.2(H)*2.8(V) (2.8inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	65K/262K colors	colors	-
Number of pixels	320(RGB)*240	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.325(H)*0.325(V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	ILI9341	-	-
Display mode	Transmissive/Normally Black	-	-
Operating temperature	-10~+50	°C	-
Storage temperature	-20~+80	°C	-

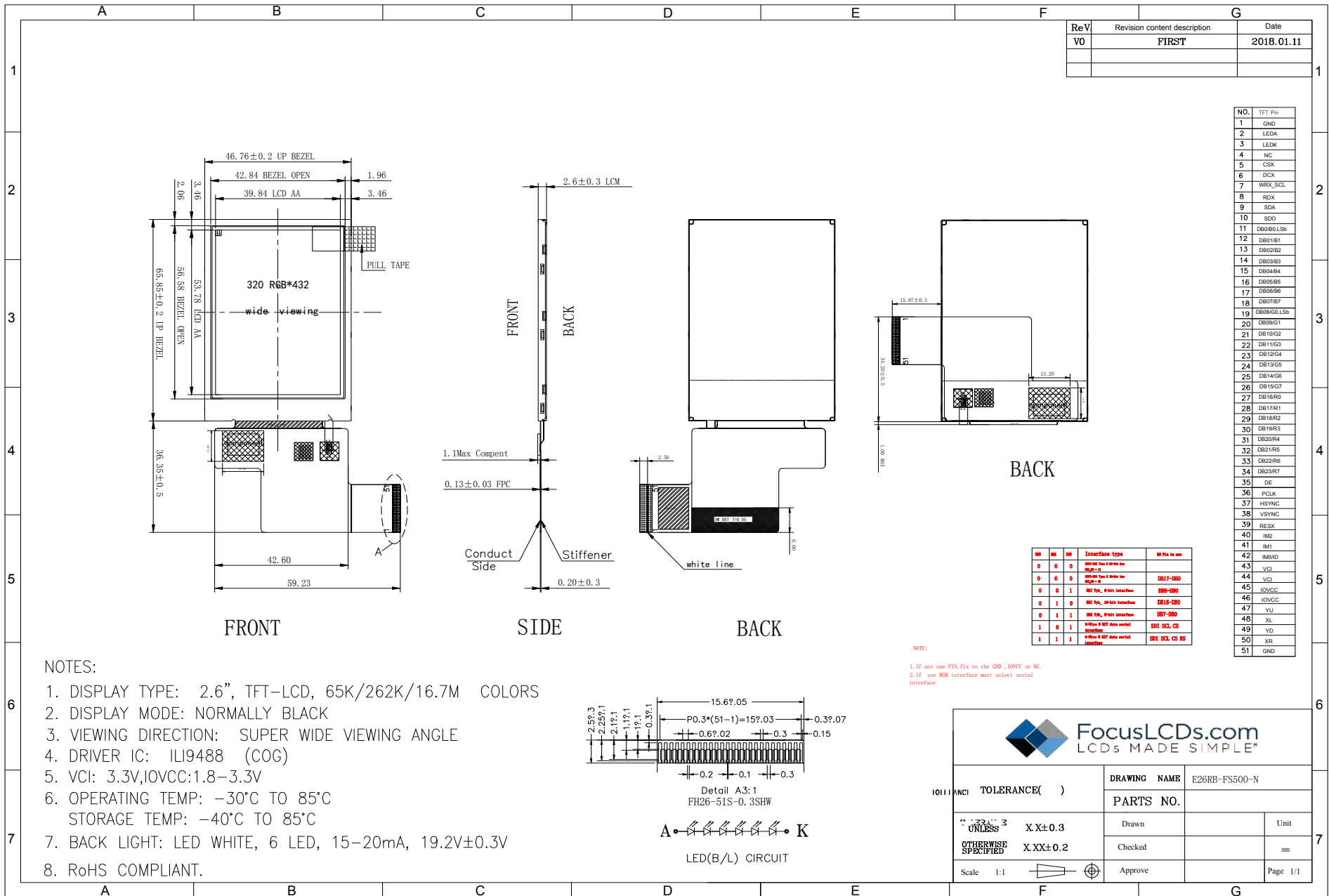
Mechanical Information

Item		Min	Typ.	Max	Unit	Note
Module size	Horizontal(H)		48		mm	-
	Vertical(V)		60		mm	-
	Depth(D)		12		mm	-
Weight			20		g	-

1. Block Diagram



2. Outline dimensions



3. Input Terminal Pin Assignment

Recommended Connector: FH26-51S-0.3SHW

NO.	Symbol	Description	I/O
1	GND	Ground.	P
2	LEDA	Cathode pin of backlight.	P
3	LEDK	Cathode pin of backlight.	P
4	NC	--	P
5	CSX	Chip select input pin ("Low" enable). Fix this pin at VCI or GND when not in use.	I
6	DCX	Display data/command selection pin	I
7	WR(SPI_SCL)	DBI Type B: WRX pin, serves as a write signal DBI Type C: SCL pin as Serial Clock when operates in the serial interface	I
8	RDX	Serves as a read signal and MCU read data at the rising edge. Fix this pin at VCI or GND when not in use.	I
9	SDA	Serial input signal. The data is applied on the rising edge of the SCL signal. If not used, fix this pin at VCI or GND.	I/O
10	SDO	Serial data output pin in serial bus system interface. If not used, please open this pin.	O
11-34	DB0-DB23	24-bit parallel bi-directional data bus for MCU system and RGB interface mode. Fix to GND level when not in use	I/O
35	DE	Data enable signal for RGB interface operation. Fix this pin at VCI or GND when not in use.	I
36	PCLK	Dot clock signal for RGB interface operation Fix this pin at VCI or GND when not in use.	I
37	HSYNC	Line synchronizing signal for RGB interface operation. Fix this pin at VCI or GND when not in use	I
38	VSYNC	Frame synchronizing signal for RGB interface operation. Fix this pin at VCI or GND when not in use.	I
39	RESX	This signal will reset the device and must be applied to properly initialize the chip.	I
40	IM2	MPU Parallel interface bus and serial interface select If use RGB Interface must select serial interface. Fix this pin at VCI and GND.	I
41	IM1		
42	IM0		
43	VCI	Supply voltage (3.3V).	P
44	VCI		
45	IOVCC	Supply voltage For IO (1.8-3.3V)	P
46	IOVCC		
47	YU	Touch panel Top Film Terminal	A/D
48	XL	Touch panel Left Glass Terminal	A/D
49	YD	Touch panel Bottom Film Terminal	A/D
50	XR	Touch panel Right Glass Terminal	A/D
51	GND	Ground	P

4. LCD Optical Characteristics

4.1 Optical specification

4.1.1 Transmissive mode

Item		Symbol	Condition	Min	Typ.	Max	Unit	Note
Contrast Ratio		CR	$\theta=0$ Normal viewing angle	--	80	150		(2)
Response time	Rising	TR+TF		--	25	50	msec	(4)
	Falling							
Color gamut		S (%)		--	58	--	%	(5)
Color Filter Chromaticity	White	W_x		0.261	0.311	0.361		(1)(5)
		W_y		0.287	0.337	0.387		
	Red	R_x		0.456	0.506	0.556		
		R_y		0.270	0.320	0.370		
	Green	G_x		0.289	0.339	0.389		
		G_y		0.50	0.550	0.60		
Blue	B_x		0.123	0.173	0.223			
	B_y		0.072	0.122	0.172			
Viewing angle	Hor.	θ_L	CR>10	60	80	--		(1) (6)
		θ_R		60	80	--		
	Ver.	θ_U		60	80	--		
		θ_D		60	80	--		
Option View Direction		ALL						

4.1.2 Reflective mode

Item	Symbol	Specifications			Unit	Note
Reflection ratio (with polarizer)	R ($\theta=\phi=0^\circ$)	1	2	-	%	(3)
Reflective contrast ratio	Cr ($\theta=0^\circ$)	-	5	-		(3)
Viewing angle (Cr ≥ 2)*	θ_{21}	-	45	-	deg	(1)(6)
	θ_{22}	-	45	-		
	θ_{12}	-	45	-		
	θ_{11}	-	45	-		

4.2 Measuring conditions

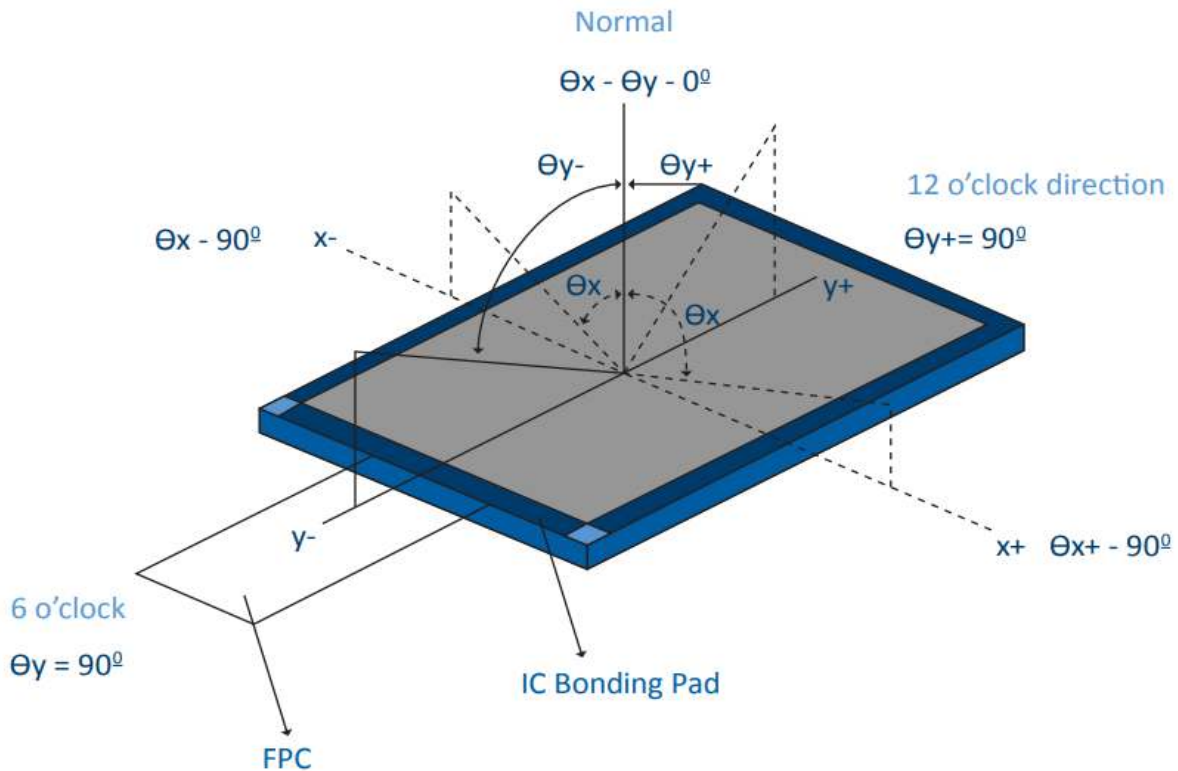
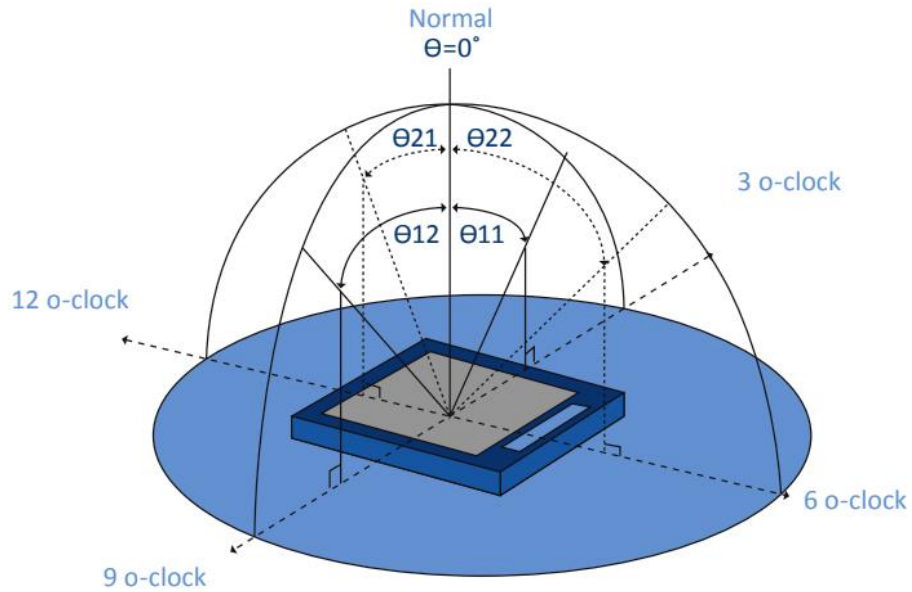
Measuring surrounding: dark room

Ambient temperature: 25±2 °C

15min. warm-up time.

Optical Specification Reference Notes:

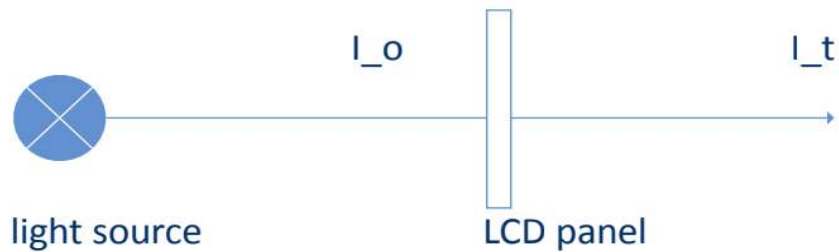
(1) Definition of Viewing Angle: The viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3,9 o'clock direction and the vertical or 6,12 o'clock direction with respect to the optical axis which is normal to the LCD surface.



(2) Definition of Contrast Ratio (Cr): measured at the center point of panel. The contrast ratio (Cr) measured on a module, is the ratio between the luminance (Lw) in a full white area (R=G=B=1) and the luminance (Ld) in a dark area (R=G=B=0).

$$Cr = \frac{L_w}{L_d}$$

(3) Definition of transmittance (T%): The transmittance of the panel including the polarizers is measured with electrical driving.



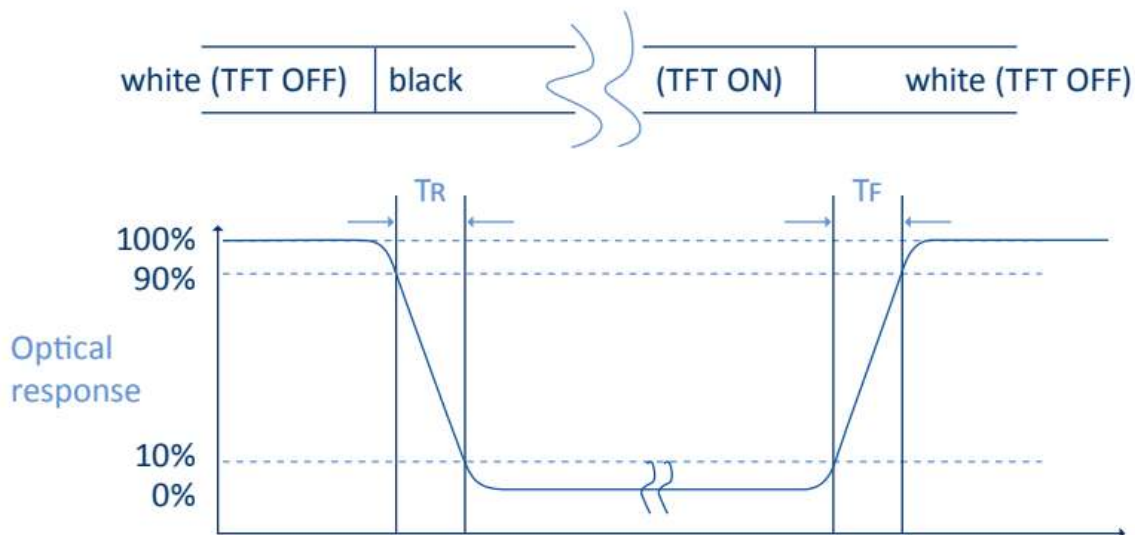
The transmittance is defined as:

$$Tr = \frac{I_t}{I_o} \times 100\%$$

I_o = the brightness of the light source.

I_t = the brightness after panel transmission

(4) Definition of Response Time (Tr, Tf): The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.



(5) Definition of Color Gamut: Measuring machine CFT-01. NTSC's Primaries: R(x,y,Y),G(x,y,Y), B(x,y,Y). FPM520 of Westar Display Technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

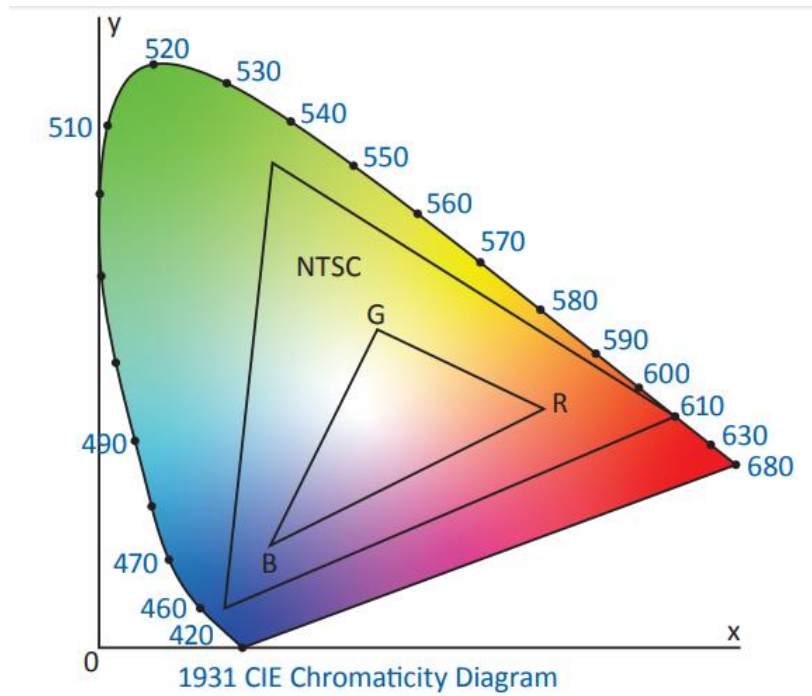
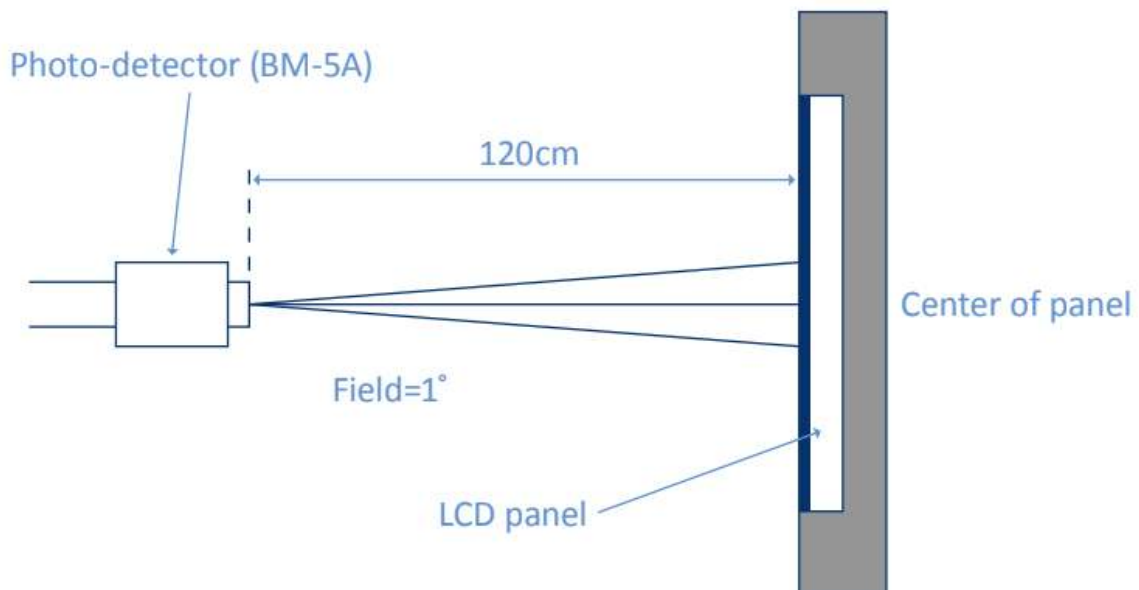


Fig. 1931 CIE chromacity diagram

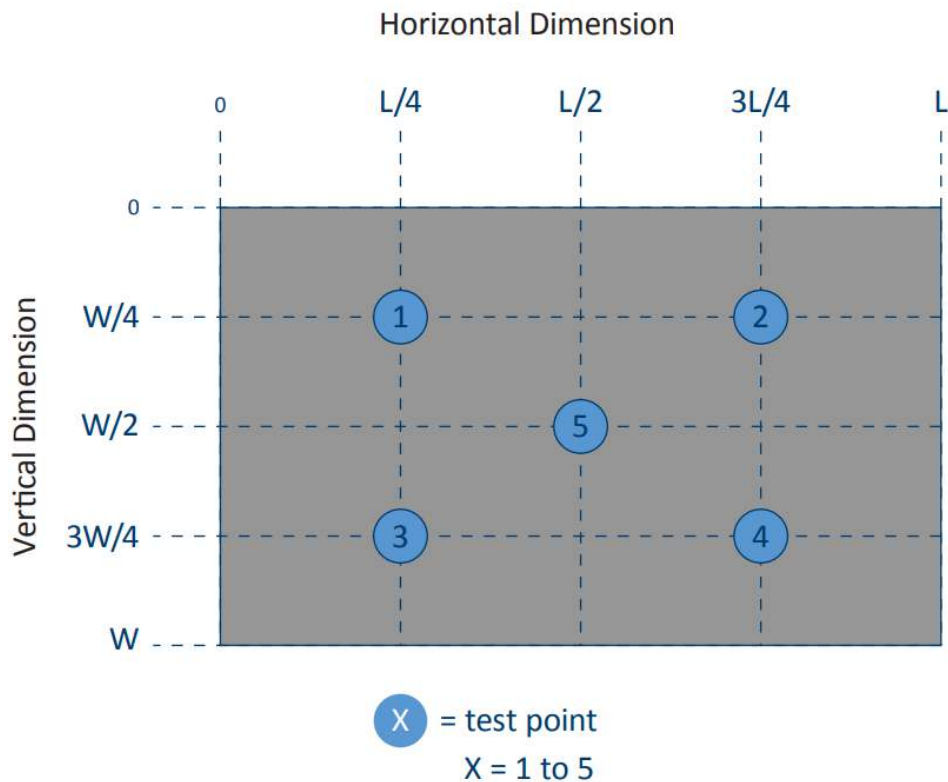
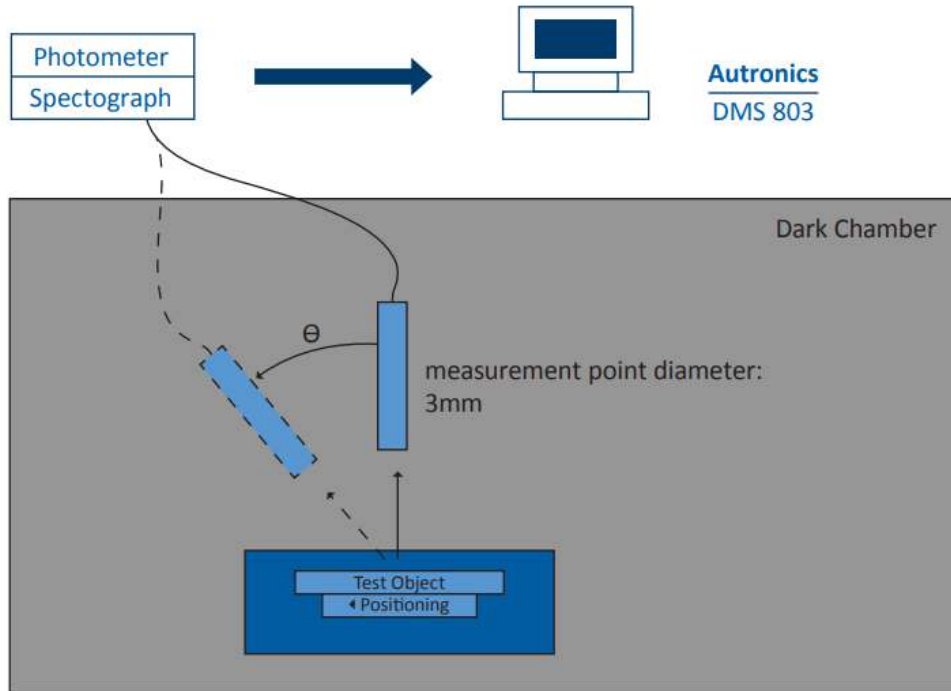
$$\text{Color gamut: } S = \frac{\text{Area of RGB triangle}}{\text{Area of NTSC triangle}} \times 100\%$$

(6) Definition of Optical Measurement Setup:



(6) Optical Measurement Setup Continued:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 20 minutes.



5. Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min	Max	Unit
Digital Supply Voltage	VCI	-0.3	3.3	V
Interface Operation Voltage	IOVCC	-0.3	3.3	V
Operating temperature	TOP	-30	+85	°C
Storage temperature	TST	-40	+85	°C

NOTE: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min	Typ.	Max	Unit	Note
Digital Supply Voltage	VCI	2.5	3.3	--	V	
Interface Operation Voltage	VDDIO	1.65	1.8	3.3	V	
Normal Mode Current Consumption	IDD	--	14	--	mA	
Level input voltage	VIH	0.7 VDDIO		VDDIO	V	
	VIL	-0.3		0.3 VDDIO	V	
Level output voltage	VOH	0.8 VDDIO		VDDIO	V	
	VOL	GND		0.2 VDDIO	V	

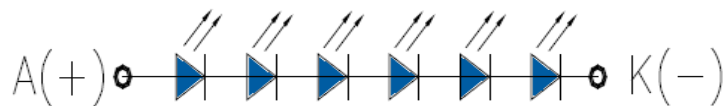
5.3 LED Backlight Characteristics

Item	Symbol	Min	Typ.	Max	Unit	Note
Forward Current	IF	15	20	--	mA	
Forward Voltage	VF	--	19.2	--	V	
LCM Luminance	LV	450	500	--	cd/m ²	Note 3
LED lifetime	Hr	50000	--	--	hour	Note1 & 2
Uniformity	AVg	80	--	--	%	Note 3

The back-light system is edge-lighting type with 6 chips White LED

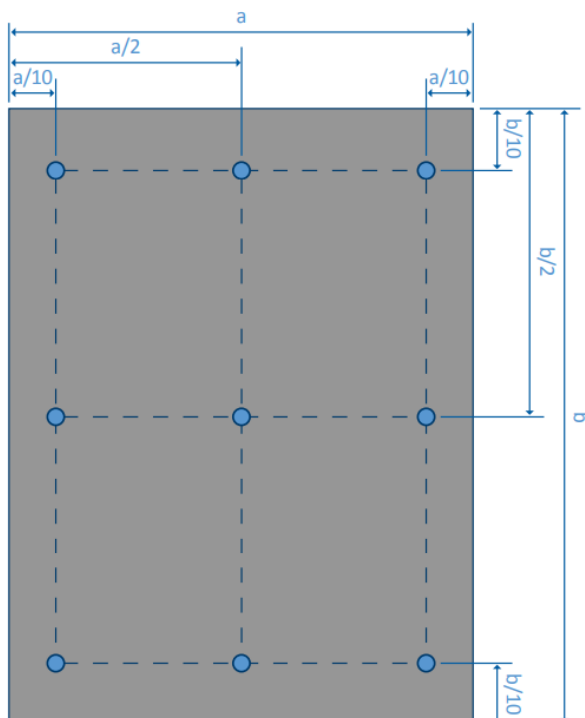
Note 1: LED lifetime (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25 ±3 °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED lifetime" is defined as the module brightness decrease to 50% original brightness at Ta=25°C and IL=20mA. The LED lifetime could be decreased if operating IL is larger than 20mA. The constant current driving method is suggested.



BLU CIRCUIT DIAGRAM

Note 3: Luminance Uniformity of these 9 points is defined as below:



$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$

$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points(1-9)}}{\text{maximum luminance in 9 points(1-9)}}$$

6. AC Characteristic

6.1 Display Parallel 16/18/24-bit Interface Characteristics

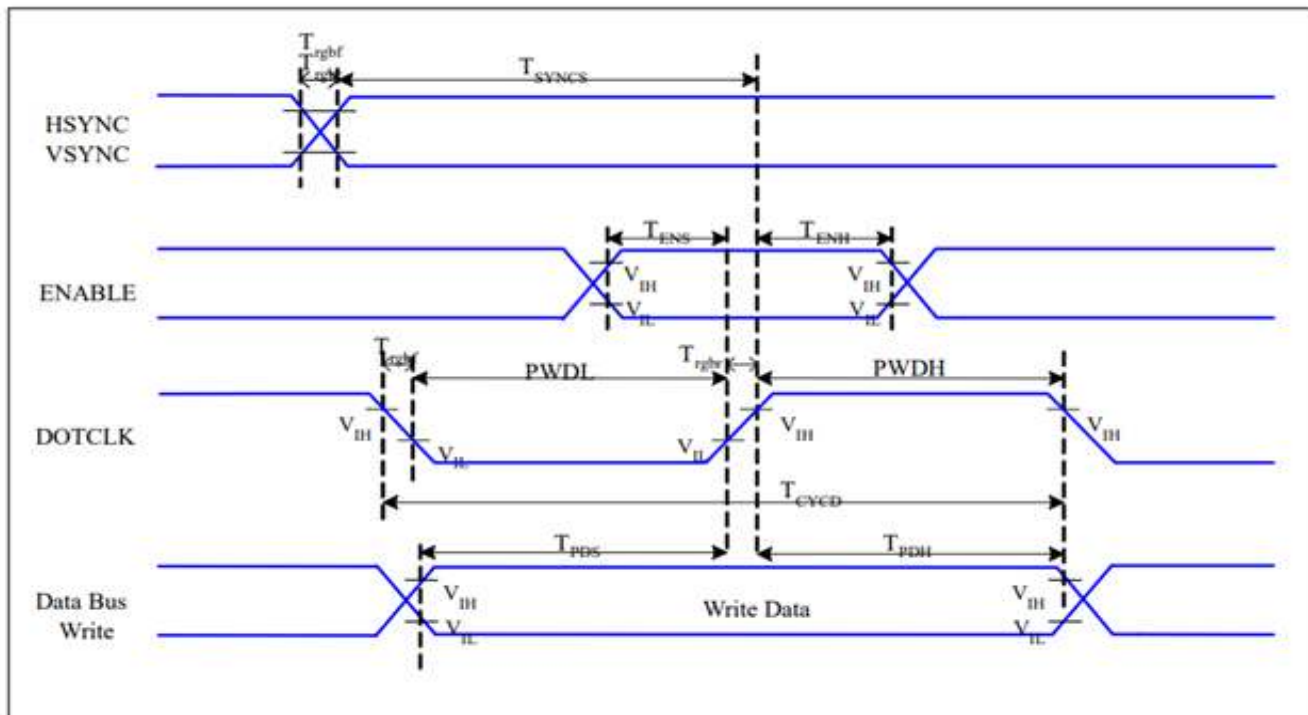
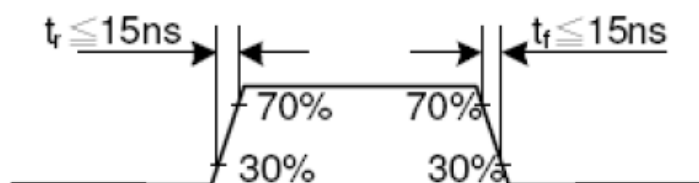


Figure 6.1: Parallel 16/18/24-Bit Interface Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Description
HSYNC/ VSYNC	T_{SYNCS}	VSYNC, HSYNC setup time	15	-	ns	18/16/6-bit bus RGB interface mode
	T_{SYNCH}	VSYNC, HSYNC hold time	15	-	ns	
DE	T_{ENS}	Enable Setup Time	15	-	ns	
	T_{ENH}	Enable Hold Time	15	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	20	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	20	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	50	-	ns	
	T_{RGHR}, T_{RGHF}	DOTCLK, HSYNC, VSYNC Rise/Fall Time	-	15	ns	
D[23:0]	T_{PDS}	Data Setup Time	15	-	ns	
	T_{PDH}	Data Hold Time	15	-	ns	

Table 6.1: 8/16 Bits RGB Interface Timing Characteristics



6.2 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

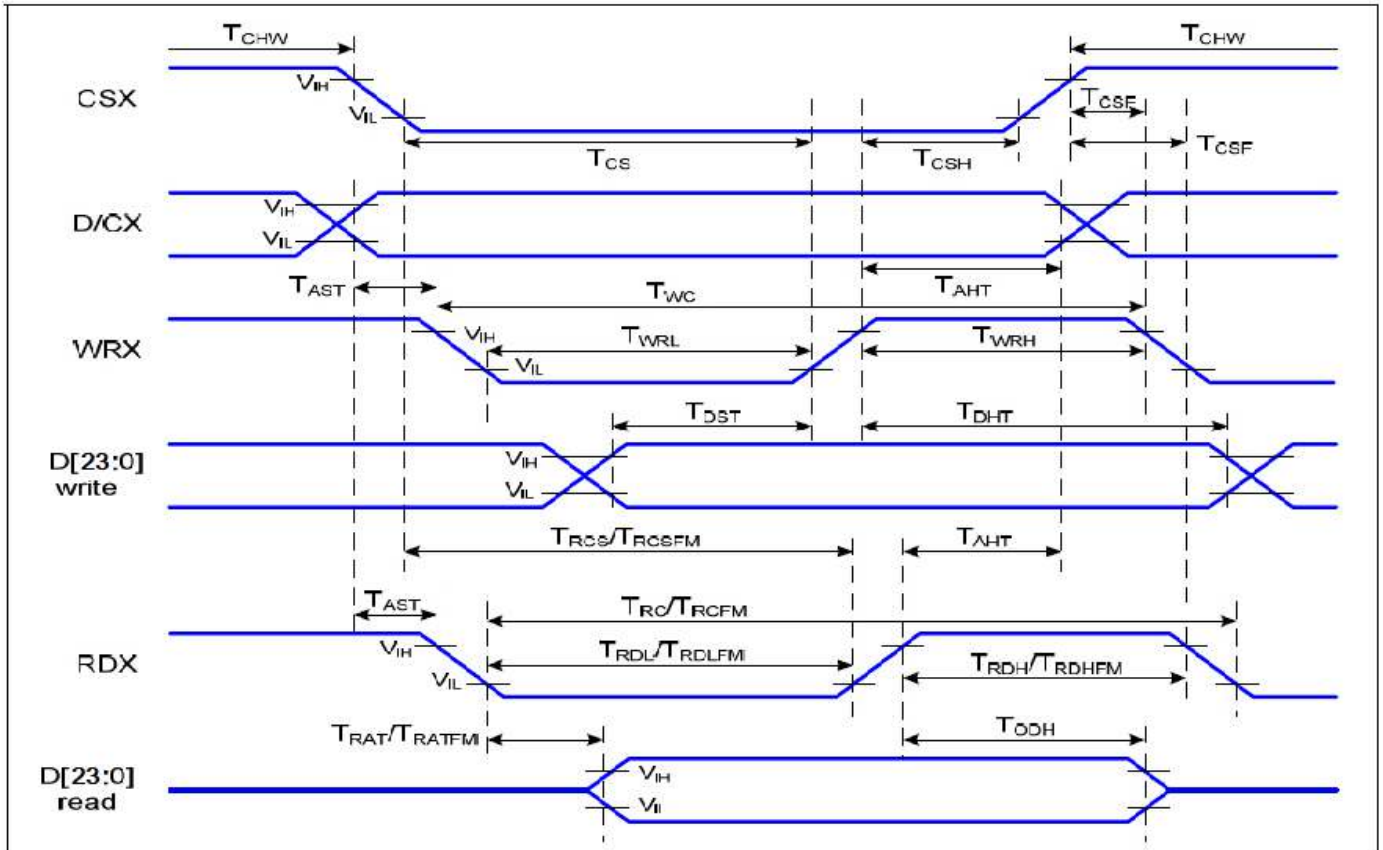
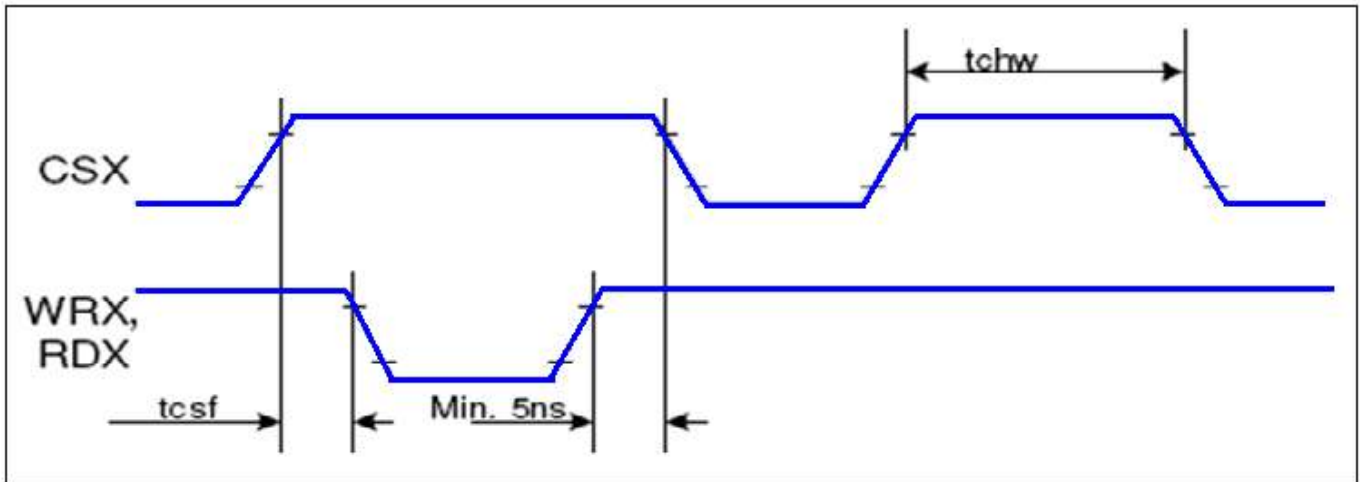


Figure 6.2: 8080 MCU Parallel Interface Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T_{AST}	Address setup time	0	-	ns	
	T_{AHT}	Address hold time (Write/Read)	0	-	ns	
CSX	T_{CHW}	Chip select "H" pulse width	0	-	ns	
	T_{CS}	Chip select setup time (Write)	15	-	ns	
	T_{RCS}	Chip select setup time (Read ID)	45	-	ns	
	T_{RCSFM}	Chip select setup time (Read FM)	355	-	ns	
	T_{CSF}	Chip select wait time (Write/Read)	10	-	ns	
	T_{CSH}	Chip select hold time	10	-	ns	
WRX	T_{WC}	Write cycle	66	-	ns	
	T_{WRH}	Control pulse "H" duration	15	-	ns	
	T_{WRL}	Control pulse "L" duration	15	-	ns	
RDX (ID)	T_{RC}	Read cycle (ID)	160	-	ns	When read ID data
	T_{RDH}	Control pulse "H" duration (ID)	90	-	ns	
	T_{RDL}	Control pulse "L" duration	45	-	ns	
RDX (FM)	T_{RCFM}	Read cycle (FM)	450	-	ns	When read from frame memory
	T_{RDHFM}	Control pulse "H" duration (FM)	90	-	ns	
	T_{RDLFM}	Control pulse "L" duration (FM)	355	-	ns	
D[23:0], D[17:0], D[15:0], D[8:0], D[7:0]	T_{DST}	Write data setup time	10	-	ns	For max CL=30pF
	T_{DHT}	Write data hold time	10	-	ns	
	T_{RAT}	Read access time (ID)	-	40	ns	For min CL=8pF
	T_{RATFM}	Read access time (FM)	-	340	ns	
	T_{ROD}	Output disable time	20	80	ns	

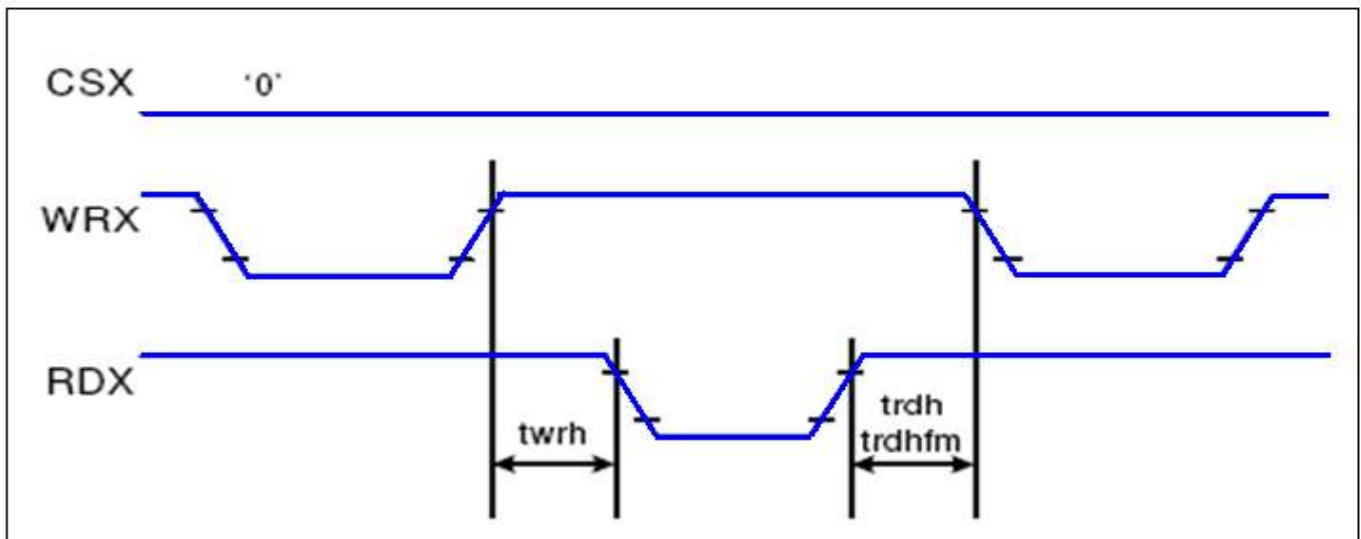
Table 6.2: 8080 MCU Parallel Interface Characteristics

CSX timings:

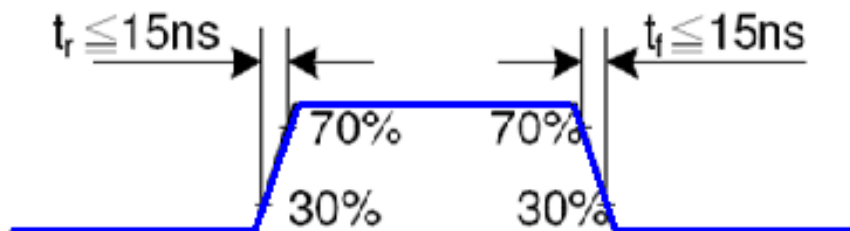


Note: Logic high and low levels are specified as 30% and 70% of IOVCC for input signals.

Write to read or read to write timings:



Note: $T_a = -30$ to 70 C, $IOVCC = 1.65V$ to $2.8V$, $VCI = 2.6V$ to $3.3V$, $GND = 0V$.



6.3 Display Serial Interface Characteristics (3-line SPI system)

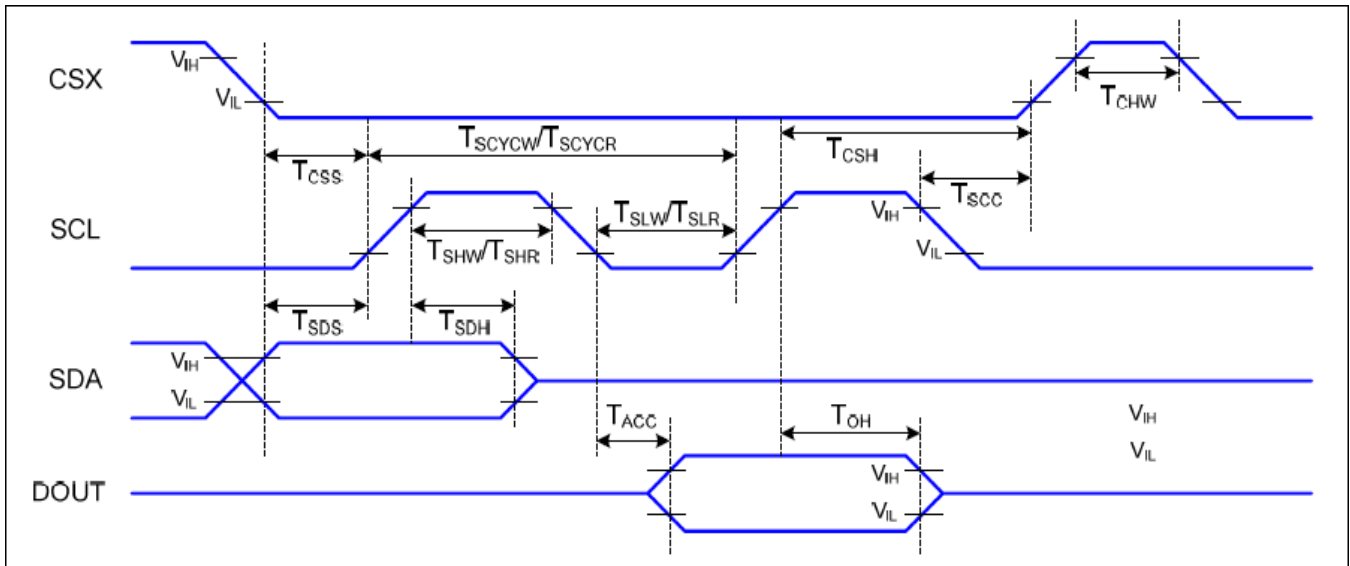


Figure 6.3: Serial Interface 3-SPI Timing Diagram

VDDI = 1.64 to 3.3V, VDD = 2.4 to 3.3V, AGND=DGND=0V, T_a = -30 to 70 C°

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T _{CSS}	Chip select setup time (write)	60		ns	
	T _{CSH}	Chip select hold time (write)	65		ns	
	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	20		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
SCL	T _{SCYCW}	Serial clock cycle (write)	100		ns	
	T _{SHW}	SCL "H" pulse width (write)	40		ns	
	T _{SLW}	SCL "L" width (write)	40		ns	
	T _{SCYCR}	Serial clock cycle (read)	150		ns	
	T _{SHR}	SCL "H" pulse width (read)	60		ns	
	T _{SLR}	SCL "L" pulse width (read)	60		ns	
SDA/SDI (Input)	T _{SDS}	Data setup time (write)	30		ns	
	T _{SDH}	Data hold time (Write)	30		ns	
SDA/SDO (Output)	T _{ACC}	Access time (read)	10	50	ns	
	T _{OH}	Output disable time (read)	10	50	ns	

Table 6.3: 3-line Serial Interface Timing Characteristics

Note: The rising time and falling time (T_r, T_f) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals

6.4 Display Serial Interface Characteristics (4-line SPI serial)

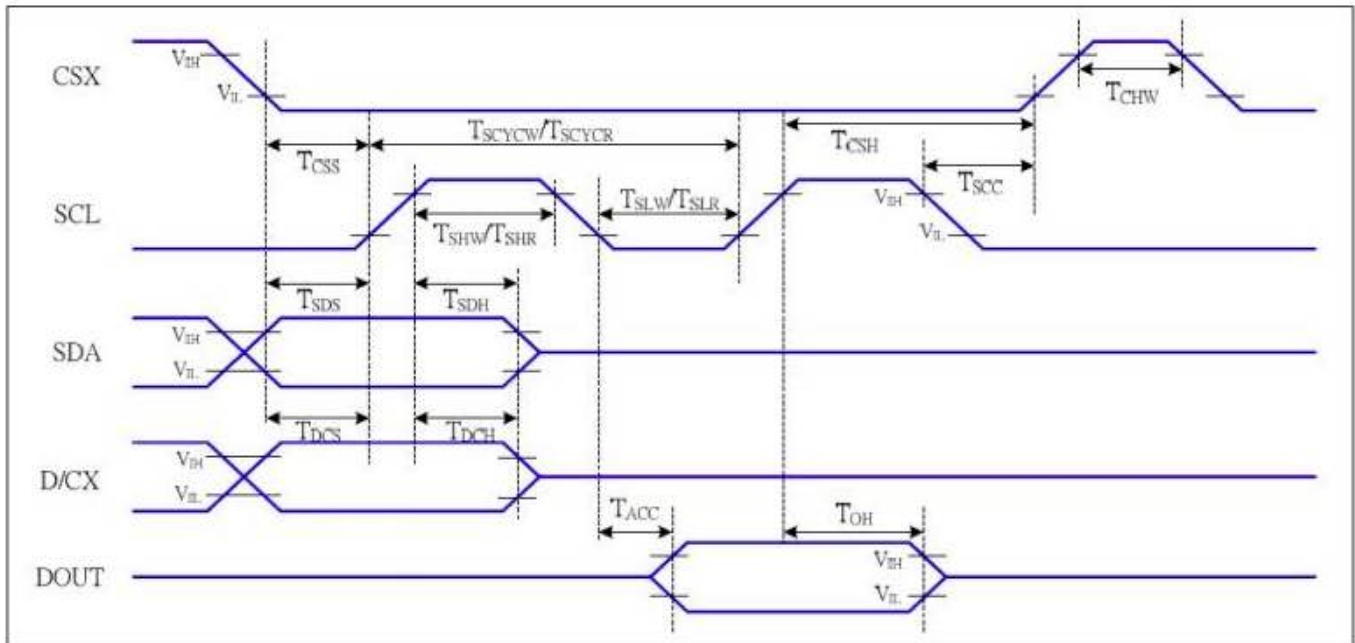


Figure 6.4: Serial Interface 4-SPI Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (read)	15		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
SCL	T _{SCYCW}	Serial clock cycle (write)	50		ns	write command & data ram
	T _{SHW}	SCL "H" pulse width (write)	10		ns	
	T _{SLW}	SCL "L" width (write)	10		ns	
	T _{SCYCR}	Serial clock cycle (read)	150		ns	read command & data ram
	T _{SHR}	SCL "H" pulse width (read)	60		ns	
	T _{SLR}	SCL "L" pulse width (read)	60		ns	
D/CX	T _{DCS}	D/CX setup time	10		ns	
	T _{DCH}	D/CX hold time	10		ns	
SDA (DIN)	T _{SDS}	Data setup time	10		ns	
	T _{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time (read)	10	50	ns	For max CL=30pF For min CL=8pF
	T _{OH}	Output disable time	15	50	ns	

Table 6.4: 4-line Serial Interface Timing Characteristics

Note: The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

6.5 Reset Timing

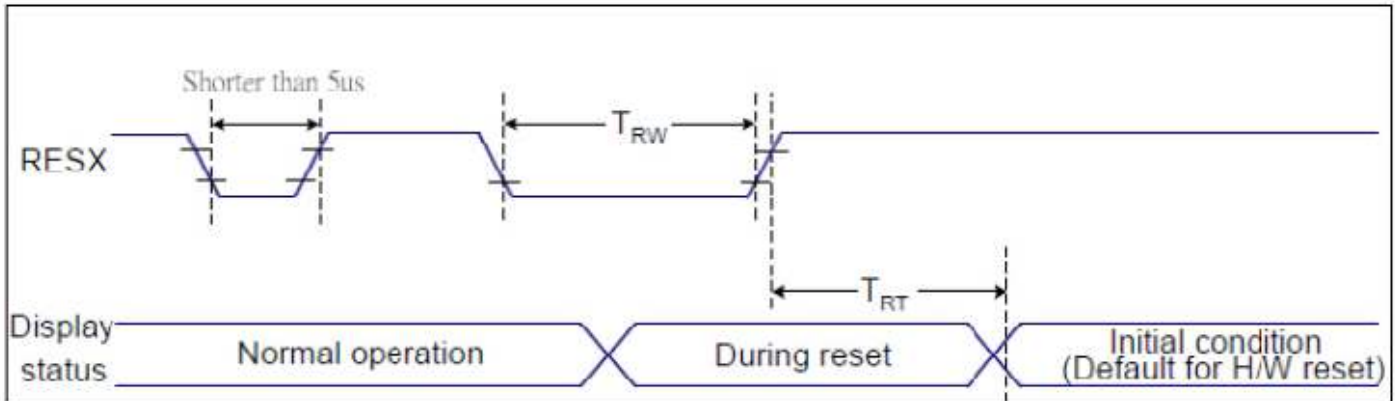


Figure 6.5: Reset Timing Diagram

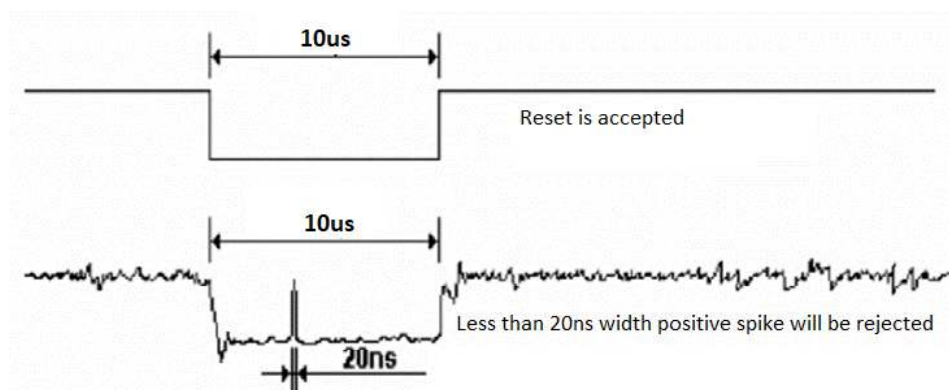
Related Pins	Symbol	Parameter	Min	Max	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1,5)	ms
				120 (Note 1, 6, 7)	ms

Notes:

- The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5ms after a rising edge of RESX.
- Spike due to an electrostatic discharge on RESX line does not because irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9 us	Reset starts

- During the resetting period, the display will be blanked (the display is entering blanking sequence, which maximum time is 120ms, when reset starts in Sleep Out mode. The display remains the blank state in Sleep in mode) and then return to Default condition for Hardware Reset.
- Spike Rejection also applies during a valid reset pulse as shown below:



- When Reset applied during Sleep In Mode.
- When Reset applied during Sleep Out Mode.
- It is necessary to wait 5ms after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120ms.

7. Cautions and Handling Precautions

7.1 Handling and Operating the Module

1. When the module is assembled, it should be attached to the system firmly. Do not warp or twist the module during assembly work.
2. Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
3. Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
4. Do not allow drops of water or chemicals to remain on the display surface. If you have the droplets for a long time, staining and discoloration may occur.
5. If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
6. The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane. Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
7. If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
8. Protect the module from static; it may cause damage to the CMOS ICs.
9. Use finger stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
10. Do not disassemble the module.
11. Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
12. Pins of I/F connector shall not be touched directly with bare hands.
13. Do not connect, disconnect the module in the “Power ON” condition.
14. Power supply should always be turned on/off by the item Power On Sequence & Power Off Sequence

7.2 Storage and Transportation

1. Do not leave the panel in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
2. Do not store the TFT-LCD module in direct sunlight.
3. The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
4. It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module. In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
5. This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.